

The Sustained Oscillation Modeling and Its Quantitative Suppression Methodology for GaN Devices

Jian Chen ¹, Student Member, IEEE, Quanming Luo ², Member, IEEE, Yuqi Wei ³, Student Member, IEEE, Xinyue Zhang, and Xiong Du ⁴, Member, IEEE

Abstract—Gallium nitride (GaN) devices are widely used due to their excellent performance when integrated into power electronics applications. However, owing to their low parasitic parameters and fast switching speed, they are more prone to instability than the silicon devices. The sustained oscillation discussed in this article is one of the instability problems, which may result in overshoot or even more serious device breakdown; thus, it is pretty necessary to suppress it effectively in practical applications. It is the first time to adopt an RC snubber to suppress the sustained oscillation in this article, which is very simple and cheap but effective. First, the sustained oscillation modeling based on a double pulse circuit is carried out. Then, the RC region is established quantitatively according to the root locus analysis results, which makes up for the defects of these qualitative methods before. Furthermore, it is first found that the sustained oscillation can be fully suppressed due to the existence of dipoles. Finally, the oscillation suppression effect within the RC region is compared with that outside the region by the simulation and experimental results, which are consistent with the theoretical analysis. Additionally, the possible negative influence of the added RC snubber is also discussed in this article, which shows that it has a little impact on the switching speed and energy loss, while the sustained oscillation is well suppressed.

Index Terms—eGaN high electron mobility transistor (HEMTs), RC snubber, sustained oscillation.

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Jian Chen, Xinyue Zhang, and Xiong Du are with the State Key Laboratory of Power Transmission Equipment and System Security and New Technology, School of Electrical Engineering, Chongqing University, Chongqing 400044, China (e-mail: 1746002496@qq.com; 20181113088t@cqu.edu.cn; duxiong@cqu.edu.cn).

Quanming Luo is with the State Key Laboratory of Power Transmission Equipment and System Security and New Technology, School of Electrical Engineering, Chongqing University, Chongqing 400044, China, and also with the School of Electrical Engineering, Shaanxi University of Technology, Hanzhong 723001, China (e-mail: lqm394@126.com).

Yuqi Wei is with the Department of Electrical Engineering, Chongqing University, Chongqing 400044, China, and also with the Department of Electrical Engineering, University of Arkansas, Fayetteville, AR 72701 USA (e-mail: yuqiwei@uark.edu).

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I. INTRODUCTION

IN RECENT years, the wide bandgap devices, such as gallium nitride (GaN) transistors, are being widely used as promising devices to achieve high-frequency, high-efficiency, and high-power-density power conversion due to a better figure of merit when compared with Si MOSFETS [1]–[6]. However, the merits of low parasitic parameters and fast switching speed may also cause instability problems for GaN-based power circuits, which may result in overvoltage, excessive electromagnetic interference, and even device breakdown [7], [9]. Specifically, the two main reasons are as follows [7]–[14]. On the one hand, the high change rate of the drain current produces a voltage across the common source inductor, which can cause a high gate–source voltage. On the other hand, the rapid change rate of the drain–source voltage produces a current in the gate–drain capacitor, and this current charges the gate–source capacitor, which can also cause a high gate–source voltage. To a certain extent, these two aspects act as a triggering mechanism leading to the onset of instability problems.

In [7], the divergence oscillation of the cascode GaN device under high-current turn-OFF condition has been studied. The capacitance mismatch between the GaN device and Si MOSFET may result in the oscillation. A simple solution is proposed by adding an additional capacitor in parallel with the Si MOSFET. In [13]–[15], the negative resistance theory and Barkhausen criterion are adopted to investigate the instability of SiC-based circuits, and some qualitative conclusions are given to suppress the occurrence of instability problems. For example, a small stray gate-loop inductance and high ON-resistance can reduce the risk of this instability. In addition, the false triggering oscillation (self-sustained oscillation) of the gate–source voltage in different devices is also studied in [16]–[22]. These studies consider various parasitic parameters and explore the effects of these parameters on the false triggering oscillation. It is found that reducing the gate inductance and common source inductance and increasing the gate resistance can suppress the false triggering oscillation to a certain extent. Besides the above problems, another instability problem is observed in the enhancement-mode GaN devices based half-bridge circuit [9]. The oscillation occurs when the active switch Q_2 is OFF and the inactive switch Q_1 conducts reversely, while the gate–source voltage v_{gs2} of Q_2 is normal, which means that Q_2 is normally turned OFF and v_{gs2}

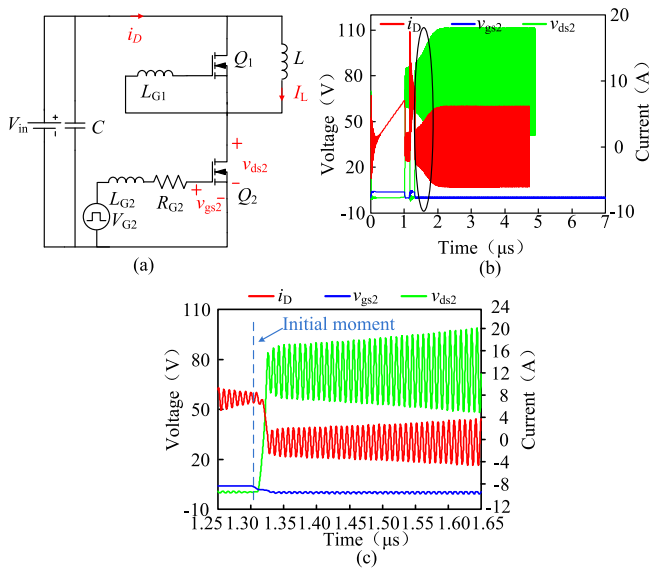


Fig. 1. Sustained oscillation of the half-bridge circuit. (a) GaN-based half-bridge circuit. (b) Sustained oscillation waveform. (c) Enlarged sustained oscillation waveform.

does not exceed the threshold voltage and cause false turn-ON, as shown in Fig. 1. Therefore, v_{gs2} is approximately clamped to 0 after Q_2 is turned OFF. In addition, it is noticeable that this oscillation phenomenon only occurs in GaN devices and does not occur in Si- or SiC-based circuits due to the unique reverse conduction characteristics of GaN devices. In [9], the influence of some parasitic parameters on this oscillation is explored and some suggestions are given to suppress this oscillation, such as reducing the common source inductance and increasing the gate resistance. However, these methods are qualitative and the suppression effects of them are quite limited. Accordingly, it is pretty necessary to find a quantitative method to solve the sustained oscillation problem to improve reliability in practical applications.

The RC snubber has been widely used to suppress the switching oscillations [23]–[30]. In [23] and [24], an RC snubber is adopted to suppress parasitic ringing in the circuit. However, the values of the RC parameters are given directly without explanation. Moreover, the theoretical analysis of their effect mechanism on parasitic ringing is not addressed, and only qualitative analysis is presented. In [25]–[29], some quantitative design methods for RC parameters are studied. However, the RC parameters are decided individually based on the designer’s experience [25]–[27], which may not guarantee a sufficient level of ringing suppression. In [25] and [26], a second-order design method is proposed to roughly estimate the RC parameters, and the RC parameters are finally fixed by the experimental results. Obviously, this design method does not provide the adequate guidance for the quantitative design of RC parameters. An analytical technique for designing the RC snubber for the half-bridge configuration and the flyback converter is proposed in [28] and [29], respectively. Different from the article presented in [25] and [26], they use the root locus method to realize the quantitative design of the RC parameters of the third-order

circuit, which achieved a better ringing suppression effect than the second-order design method in [25] and [26]. However, these quantitative methods for the RC design can only be applied to second-order or third-order circuits. In [30], the RC snubber is employed to suppress the false triggering oscillation of v_{gs2} by adding it across the gate–source terminal of the switch. Although the oscillation is not fully suppressed, the effect is satisfactory, and the RC design method can provide some guidance for high-order systems. However, since the sustained oscillation of v_{ds2} only occurs in GaN devices, it is doubtful whether the RC snubber can be used to suppress this oscillation satisfactorily or not due to the different oscillation mechanism between them. In addition, due to the different models of them, the design method in [30] is not completely applicable.

In this article, the RC snubber is first attempted to suppress the sustained oscillation by adding it across the drain–source terminal of the switch in a double pulse circuit, and the RC regions are determined quantitatively with full or well suppression effects. In Section II, the high-frequency equivalent model, including the RC snubber, is established by considering all parasitic parameters, and then the voltage across the drain–source terminal in the s -domain is derived. According to the expression of the drain–source voltage, dipoles are found by analyzing the root locus; thus, it has the opportunity to adopt dipole elimination to achieve full suppression of the sustained oscillation. This method is instructive for high-order circuits to establish dipoles through circuit design to achieve oscillation suppression, and it can also stimulate ideas for how to analyze and improve the performance of high-order systems. And then, the RC regions are quantitatively determined in Section III. In Section IV, the theoretical analysis results are fully verified by simulations and experiments. In addition, the switching speed and the energy loss with or without the RC snubber are also compared in this section, which verify the advantages of the proposed method. The conclusion derived from this article is summarized in Section V.

II. DERIVATION AND SETTING OF AN EQUIVALENT CIRCUIT MODEL

The double pulse circuit is taken as an example to study the sustained instability problem, which includes all the parasitic parameters of the circuit and device, as shown in Fig. 2(a). Q_1 is the inactive device, Q_2 is the active device and also the device under test. The current commutation occurs after Q_2 is turned OFF. The load inductor current I_L flows through Q_1 from its source to the drain, which may cause the gate–drain voltage v_{gd} to exceed the threshold voltage. Thus, the electrons are attracted to the heterostructure interface of the aluminum gallium nitride (AlGaN) and GaN so that the 2-D electron gas is reestablished, and the GaN devices conduct reverse current [31], [32]. At this time, Q_1 operates in the active region. During this process, the sustained oscillation may occur due to the parasitic parameters and reverse conduction characteristics of the GaN device.

In order to obtain the high-frequency equivalent circuit diagram of Fig. 2(a), the following assumptions are made.

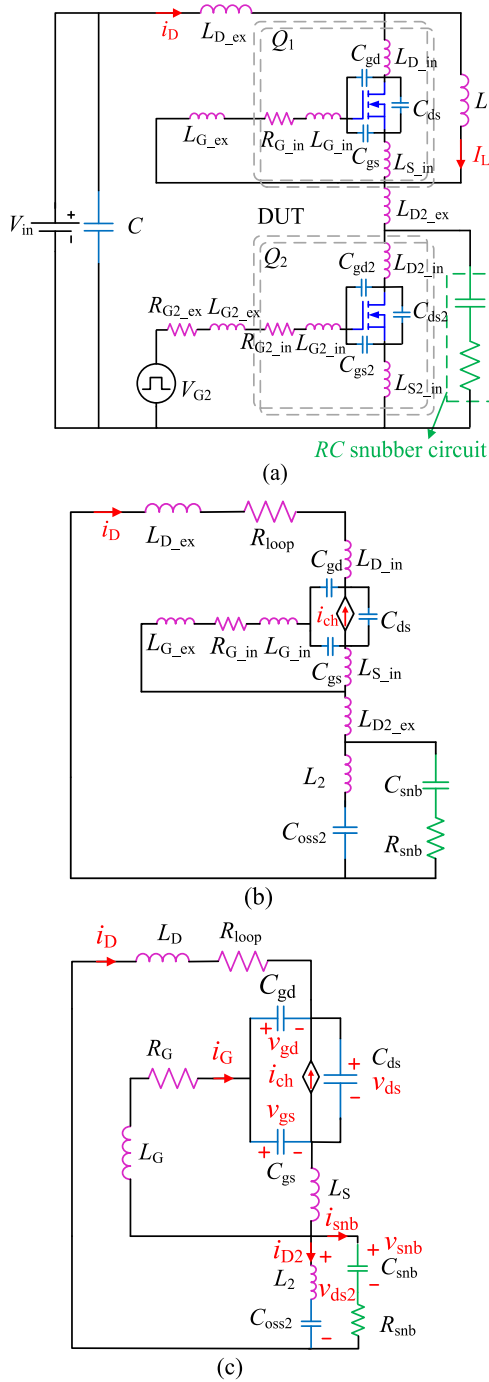


Fig. 2. (a) Schematic diagram of double pulse circuit with RC snubber circuit. (b) Simplified equivalent circuit. (c) Final high-frequency equivalent circuit.

- 1) Since the sustained oscillation occurs after Q_2 is turned OFF, and the gate–source voltage v_{gs2} of Q_2 is normal (v_{gs2} is approximately clamped to 0 after Q_2 is turned OFF), as shown in Fig. 1(c). Thus, the gate and source terminals of Q_2 are approximately shorted and only its output capacitor C_{oss2} is considered.
- 2) The decoupling capacitor C can be regarded as a shorted component due to its large capacitance, and its high-frequency impedance is sufficiently smaller than the other parameters.

TABLE I
DEFINITIONS OF THE SYMBOLS

Symbol	Description
V_{in}	Input voltage
L_D	Drain inductance, sum of L_{D_ex} , L_{D_in} and L_{D2_ex}
L	Inductance of load inductor
L_G	Gate inductance of Q_1 , sum of L_{G_ex} and L_{G_in}
L_S	Common source inductance of Q_1 , that is L_{S_in}
L_2	Parasitic inductance of Q_2 , sum of L_{D2_in} and L_{S2_in}
C	Capacitance of decoupling capacitor
C_{ds}	Drain-source capacitance of Q_1
C_{gs}	Gate-source capacitance of Q_1
C_{gd}	Gate-drain capacitance of Q_1
C_{oss2}	Output capacitance of Q_2
C_{snb}	Capacitance of snubber capacitor
R_{loop}	Power loop resistance
R_G	Gate resistance of Q_1 , that is R_{G_in}
R_{snb}	Resistance of snubber resistor
g_m	Reverse transconductance
i_D	Drain current of Q_1
i_G	Gate current of Q_1
i_{D2}	Output capacitance current of Q_2
i_{snb}	Current of snubber circuit
v_{ds}	Drain-source voltage of Q_1
v_{gs}	Gate-source voltage of Q_1
v_{gd}	Gate-drain voltage of Q_1
v_{gs2}	Gate-source voltage of Q_2
v_{ds2}	Drain-source voltage of Q_2
v_{snb}	Snubber capacitor voltage

- 3) The load inductor L can be regarded as an open component due to its large inductance, and its high-frequency impedance is sufficiently larger than the other parameters.
- 4) The inductor current charges the output capacitor of Q_1 reversely after Q_2 is turned OFF, which will cause an increase in v_{gd} , and Q_1 starts to conduct after v_{gd} exceeds its threshold voltage. Accordingly, Q_1 works in the active region and will have the channel current when the sustained oscillation of Q_2 occurs [9].

Based on these assumptions above, the simplified equivalent circuit is shown in Fig. 2(b). By integrating some components together, the final high-frequency equivalent circuit diagram is derived, as shown in Fig. 2(c), where L_D is the sum of the inductances L_{D_ex} , L_{D_in} , and L_{D2_ex} , the sum of L_{G_ex} and L_{G_in} is represented by L_G , L_2 is the sum of the inductances L_{D2_in} and L_{S2_in} , the parasitic gate resistance R_{G_in} and the common source inductance L_{S_in} are represented by R_G and L_S , respectively. The definitions of the main symbols used in this article are given in Table I.

From Fig. 2(c), the following equations are derived as:

$$0 = L_D \frac{di_D}{dt} + R_{loop} i_D + v_{ds} + L_S \frac{d(i_G + i_D)}{dt} + v_{ds2} \quad (1)$$

$$i_G = C_{gs} \frac{dv_{gs}}{dt} + C_{gd} \frac{dv_{gd}}{dt} = C_{iss} \frac{dv_{gs}}{dt} - C_{gd} \frac{dv_{ds}}{dt} \quad (2)$$

$$i_D = C_{ds} \frac{dv_{ds}}{dt} - C_{gd} \frac{dv_{gd}}{dt} - i_{ch} = C_{oss} \frac{dv_{ds}}{dt} - C_{gd} \frac{dv_{gs}}{dt} - i_{ch} \quad (3)$$

$$i_{ch} = g_m v_{gd} = g_m (v_{gs} - v_{ds}) \quad (4)$$

$$0 = L_G \frac{di_G}{dt} + i_G R_G + v_{gs} + L_S \frac{d(i_G + i_D)}{dt} \quad (5)$$

$$v_{ds2} = L_2 \frac{di_{D2}}{dt} + v_{C_{oss2}} \quad (6)$$

$$i_{D2} = C_{oss2} \frac{dv_{C_{oss2}}}{dt} \quad (7)$$

$$i_{snb} = C_{snb} \frac{dv_{snb}}{dt} \quad (8)$$

$$v_{ds2} = i_{snb} R_{snb} + v_{snb} \quad (9)$$

$$i_D = i_{D2} + i_{snb}. \quad (10)$$

The values of R_{snb} and C_{snb} are determined to suppress the sustained oscillation of v_{ds2} ; in the following, the s-domain equation of v_{ds2} is deduced out. The initial moment is shown in Fig. 1(c) after using the Laplace transform with the initial conditions $i_D(0) = i_{D2}(0) = I_0$, $i_G(0) = i_{snb}(0) = 0$, $v_{gs}(0) = 0$, $v_{ds}(0) = V_0$, and $v_{ds2}(0) = 0$, and the following equations are obtained as:

$$0 = (L_D + L_S)(si_D(s) - I_0) + R_{loop}i_D(s) + v_{ds}(s) + sL_Si_G(s) + v_{ds2}(s) \quad (11)$$

$$i_G(s) = sC_{iss}v_{gs}(s) - C_{gd}(sv_{ds}(s) - V_0) \quad (12)$$

$$i_D(s) = C_{oss}(sv_{ds}(s) - V_0) - sC_{gd}v_{gs}(s) - g_m(v_{gs}(s) - v_{ds}(s)) \quad (13)$$

$$0 = sL_Gi_G(s) + R_Gi_G(s) + v_{gs}(s) + sL_Si_G(s) + L_S(si_D(s) - I_0) \quad (14)$$

$$i_D(s) = \frac{sC_{oss2}v_{ds2}(s) + sC_{oss2}L_2I_0}{1 + s^2C_{oss2}L_2} + \frac{sC_{snb}v_{ds2}(s)}{sR_{snb}C_{snb} + 1} \quad (15)$$

where $i_D(s)$, $i_G(s)$, $v_{gs}(s)$, $v_{ds}(s)$, and $v_{ds2}(s)$ are defined as the Laplace transforms of i_D , i_G , v_{gs} , v_{ds} , and v_{ds2} , respectively.

From (11)–(15), the following expression of v_{ds2} is then derived as

$$v_{ds2}(s) = \frac{N(s)}{M(s)} = \frac{a_0s^5 + a_1s^4 + a_2s^3 + a_3s^2 + a_4s + a_5}{b_0s^7 + b_1s^6 + b_2s^5 + b_3s^4 + b_4s^3 + b_5s^2 + b_6s + b_7} \quad (16)$$

where coefficients b_i ($i = 0, 1, 2, 3, 4, 5, 6, 7$) and a_j ($j = 0, 1, 2, 3, 4, 5$) can be derived through MATLAB, which is shown in the Appendix. From (16), it is clear that this is a seventh-order system.

III. ANALYSIS AND DESIGN METHODOLOGY FOR RC SNUBBER TO SUPPRESS THE SUSTAINED OSCILLATION

In order to determine the RC values to suppress the sustained oscillation of v_{ds2} effectively, we need to study the characteristic equation $M(s) = 0$ of $v_{ds2}(s)$. As can be seen from (16), $M(s)$ is a seventh-order polynomial. The sustained oscillation can be fully suppressed if the solutions of the characteristic equation, $M(s)$

TABLE II
KEY CIRCUIT PARAMETERS

Symbol	Value	Symbol	Value
L_D	8.0 nH	C_{gd}	0.06 nF
L_G	5.2 nH	C_{oss2}	0.19 nF
L_S	0.2 nH	R_G	1.3 Ω
L_2	0.4 nH	R_{loop}	0.2 Ω
C_{iss}	0.3 nF	g_m	10 S
C_{oss}	0.5 nF		

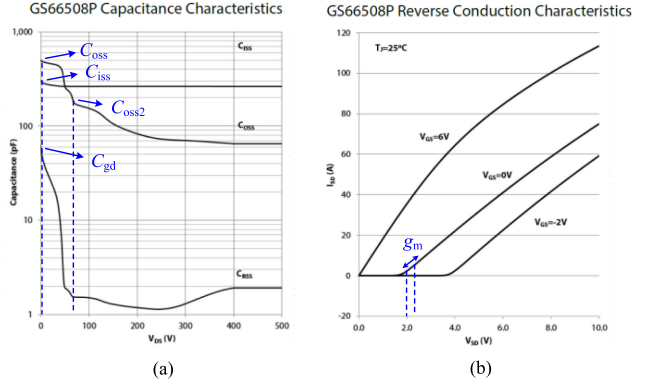


Fig. 3. (a) GS66508P capacitance characteristic diagram in the datasheet. (b) Reverse conduction characteristic of GS66508P.

$= 0$, are all negative real numbers; then, v_{ds2} has no oscillation terms. When the solution of $M(s) = 0$ is a negative real number, the damping ratio is 1. However, it cannot guarantee that all solutions of the characteristic equations above third order are negative real numbers [28]–[30]. Based on this, all solutions of the characteristic equation $M(s) = 0$ above need to be explored. The values of some important parameters are given in Table II, which are obtained according to the parameters of our experimental prototype. Specifically, parasitic inductances that include device package inductances and printed circuit board (PCB) trace parasitic inductances are obtained through the LTspice model of the device and ANSYS Q3D extraction software, respectively. The transconductance and capacitances are obtained from the device datasheet [33]. It needs to be mentioned here that R_{loop} only contains dc resistance because the high-frequency ac resistance is much smaller than the dc resistance 0.2 Ω ; thus, it can be ignored. After Q_2 is turned OFF, since the central tendency of the drain–source voltage of Q_2 is V_{in} , the capacitances of Q_1 are obtained around $V_{ds} = 0$ and the capacitance of Q_2 is approximately obtained at V_{in} . The transconductance g_m is obtained around the threshold voltage. The specific method of obtaining capacitances and transconductance is shown in Fig. 3.

When the RC snubber is not added, that is, R_{snb} and C_{snb} are equal to 0 so that $N(s)$ and $M(s)$ in (16) are fourth-order and fifth-order polynomials, respectively. Fig. 4 shows the pole-zero map of $v_{ds2}(s)$ without the RC snubber. It can be observed that there are four zeros and five poles in Fig. 4(a). The five poles are a real pole p_1 and two pairs of complex conjugate poles p_2 , p_2^* and p_3 , p_3^* . The real pole p_1 is negative and farther from the imaginary axis than p_2 and p_3 ; thus, it does not affect the stability of the system. It can be seen from Fig. 4(b) that p_3 , p_3^* are much closer to the imaginary axis than p_2 , p_2^* ; therefore, p_3 ,

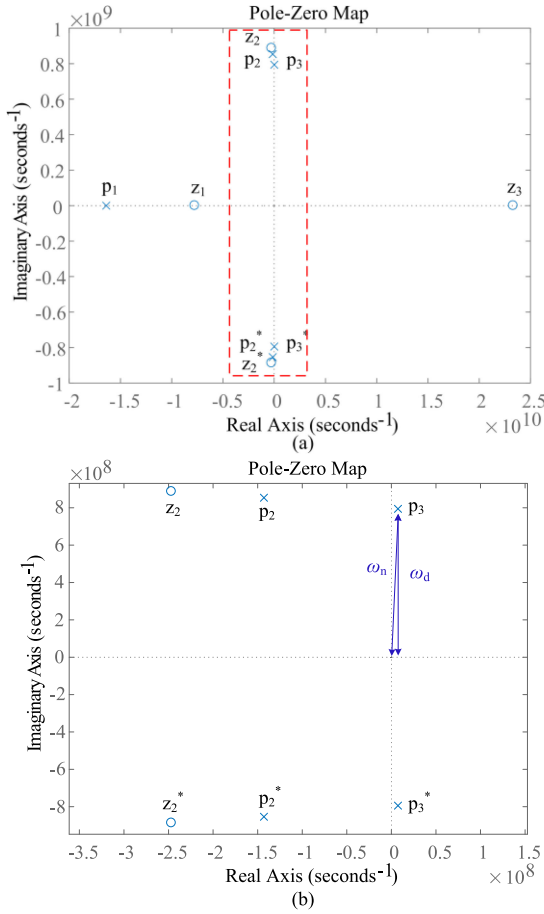


Fig. 4. Pole-zero map of $v_{ds2}(s)$ without the RC snubber circuit. (a) Pole-zero map of the $v_{ds2}(s)$. (b) Enlarged view.

p_3^* are the two dominant poles and they determine the stability of the system to a great extent.

The complex poles p_3, p_3^* can be defined by their real and imaginary parts as

$$p_3, p_3^* = \sigma \pm j\omega_d. \quad (17)$$

Hence, similar to the second-order system, the damping ratio ζ can be derived as (18) [34]. In addition, since the dominant pole p_3 is very close to the imaginary axis, the oscillation frequency can be approximately calculated, as shown in (19)

$$\zeta = \frac{-\sigma}{|P_3|} = \frac{-\sigma}{\sqrt{\sigma^2 + \omega_d^2}} = \frac{-\sigma}{\omega_n} \quad (18)$$

$$f_d \approx \frac{\omega_d}{2\pi}. \quad (19)$$

The damping ratio ζ can reflect the damping characteristic of $v_{ds2}(t)$. The larger the damping ratio ζ , the easier the oscillation is to be damped. Since p_3, p_3^* are located in the right-half plane of s , p_3, p_3^* have a positive real part, and ζ is less than 0. Therefore, the system is unstable, and the sustained oscillation of v_{ds2} will occur. If $\zeta > 0$ when the RC snubber is added, the poles have a negative real part and this sustained oscillation will disappear.

After the RC snubber is included, the characteristic equation $M(s) = 0$ is a seventh-order equation. As mentioned earlier, when all solutions of the characteristic equation are negative

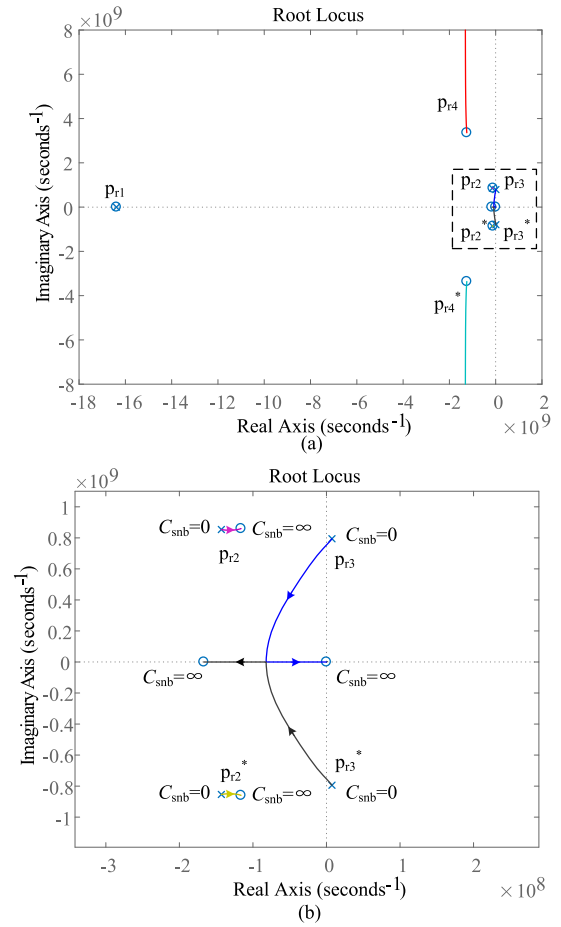


Fig. 5. (a) Root locus diagram of $M(s) = 0$ for parameter C_{snb} ($R_{snb} = 1 \Omega$). (b) Enlarged root locus diagram.

real numbers, the oscillation can be sufficiently suppressed. Therefore, it needs to study the root locus of all solutions of $M(s) = 0$. Considering C_{snb} as a variable and the equation $M(s) = 0$ can be transformed into the following form:

$$M_1 = 1 + \frac{C_{snb}Q}{P} = 0. \quad (20)$$

The complete expression can be derived through MATLAB and the coefficients Q and P are shown in the Appendix.

By changing the value of the capacitance C_{snb} from zero to infinity, we can get the root locus of the characteristic equation. Fig. 5 shows the root locus of the characteristic equation $M(s) = 0$ when the RC snubber circuit is adopted ($R_{snb} = 1 \Omega$). It can be seen that after the RC snubber circuit is included, the root locus tends to the left-half plane of s . Therefore, the sustained oscillation tends to be suppressed. It can be seen from Fig. 5(a) that when C_{snb} changes from zero to infinity, the characteristic equation $M(s) = 0$ has a real solution with a damping ratio of 1 and three pairs of complex conjugate solutions. In practical applications, the effect on the system performance of the pole, which is three to six times farther away from the imaginary axis than the dominant pole, can often be ignored. In the process of C_{snb} changing from zero to infinity, p_{r1} , p_{r4} , and p_{r4}^* are always nondominant poles; thus, we can ignore their effects on

the system. In order to make this oscillation better suppressed, we only need to make the damping ratio of the other two pairs of complex conjugate solutions as large as possible. Fig. 5(b) is the enlarged view of the two pairs of complex conjugate solutions. As mentioned earlier, when all solutions of the characteristic equation $M(s) = 0$ are negative real numbers, the oscillation can be sufficiently suppressed. However, for this seventh-order equation, it is impossible to guarantee that all solutions of $M(s) = 0$ are real numbers according to Fig. 5(b).

When the snubber capacitance C_{snb} changes from zero to infinity, we can find that the poles p_{r2} and p_{r2}^* will also become the dominant poles and their damping ratios are small, which may also affect the stability of the system. At the same time, it can also be seen that during the changing of C_{snb} , the position of the poles p_{r2} and p_{r2}^* changes very little. Therefore, it is valuable to try to eliminate these poles using the zero-point equation. To this end, the dipole elimination method based on the root locus analysis to determine the R_{snb} and C_{snb} value regions quantitatively is adopted in the following for this seventh-order system.

Similar to the method above, we can get the zero-point equation $N(s) = 0$ according to (16). Considering C_{snb} as a variable and transforming the equation into the following form:

$$N_1 = 1 + \frac{C_{\text{snb}}Q_1}{P_1} = 0 \quad (21)$$

where the coefficients Q_1 and P_1 are also shown in the Appendix.

By changing the value of the capacitance C_{snb} from zero to infinity according to $C_{\text{snb}}Q_1/P_1$, we can get the root locus of $N(s) = 0$. Fig. 6 shows the root locus diagram of $N(s) = 0$ when the snubber resistance $R_{\text{snb}} = 1 \Omega$. It can be seen that there are five zero points, including three real zeros and a pair of complex conjugate zeros. It is found that the position of the pair of complex conjugate zeros z_{r2} and z_{r2}^* does not change according to Fig. 6(b). The enlarged root locus diagram of $M(s) = 0$ and $N(s) = 0$ is shown in Fig. 7. It can be seen that when C_{snb} changes from zero to infinity, the distances between the zero root loci of z_{r2} , z_{r2}^* and the pole root loci of p_{r2} , p_{r2}^* are approximately an order of magnitude smaller than their own modulus, which forms two pairs of dipoles. Therefore, the influence of the root loci of p_{r2} and p_{r2}^* on the system performance is negligible. Accordingly, we only need the root loci of p_{r3} and p_{r3}^* to have a larger damping ratio so that the oscillation is better suppressed. When the damping ratio is greater than 0.4, it will have well oscillation suppression effect [35]. Therefore, we attempt to take the damping ratio greater than 0.4 as the design standard, which will be verified by the test results in Section IV. According to Fig. 7, when $C_{\text{snb}} > 3.35 \text{ nF}$, the damping ratio of p_{r3} and p_{r3}^* is greater than 0.4, and the oscillation can be well damped. When $C_{\text{snb}} > 18.9 \text{ nF}$, the damping ratio is the largest ($\zeta = 1$), and the sustained oscillation can be fully suppressed.

Similar to the analysis above, Fig. 8 shows the root locus diagram of the characteristic equation $M(s) = 0$ and $N(s) = 0$ when the snubber resistance R_{snb} changes from 0.5 to 4 Ω . It can be seen that p_{r1} , p_{r4} , and p_{r4}^* are always nondominant poles, so we can ignore their effects. Fig. 8(b) shows the enlarged root locus diagram of $M(s) = 0$ and $N(s) = 0$. It can be seen

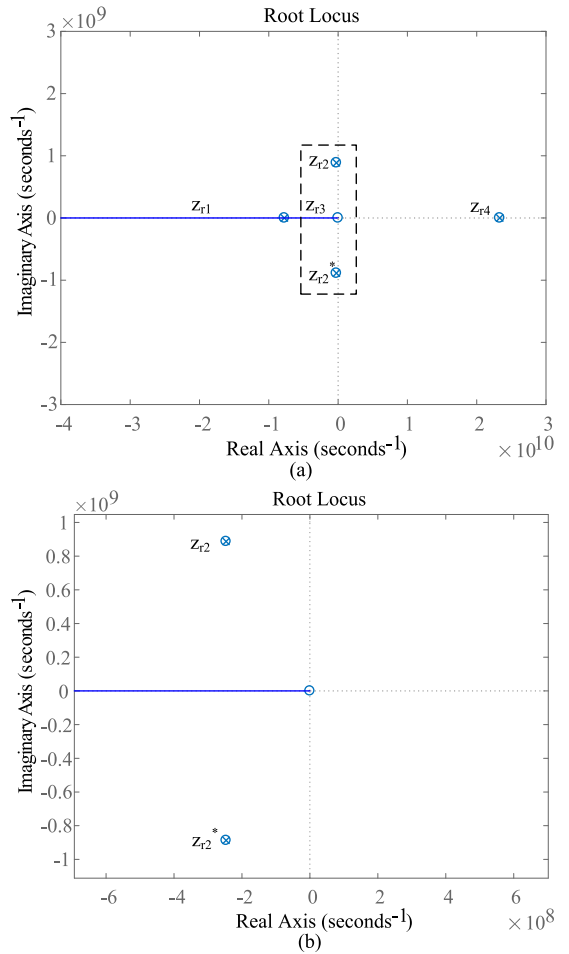


Fig. 6. (a) Root locus diagram of $N(s) = 0$ for parameter C_{snb} ($R_{\text{snb}} = 1 \Omega$). (b) Enlarged root locus diagram.

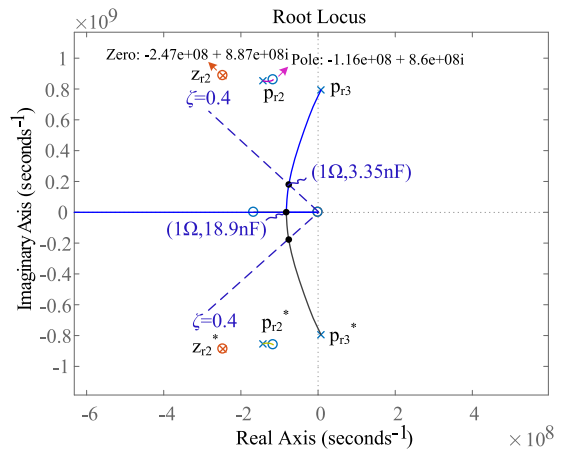


Fig. 7. Enlarged root locus diagram of $M(s) = 0$ and $N(s) = 0$ for parameter C_{snb} ($R_{\text{snb}} = 1 \Omega$).

that z_{r2} , z_{r2}^* and p_{r2} , p_{r2}^* still form dipoles in the process of C_{snb} changing from zero to infinity; thus, their impact on the system performance can be neglected. Therefore, we only need the root loci of p_{r3} and p_{r3}^* to have a large damping ratio to make the oscillation well suppressed. For example, when the snubber resistance $R_{\text{snb}} = 3 \Omega$, if $C_{\text{snb}} > 0.77 \text{ nF}$, the damping

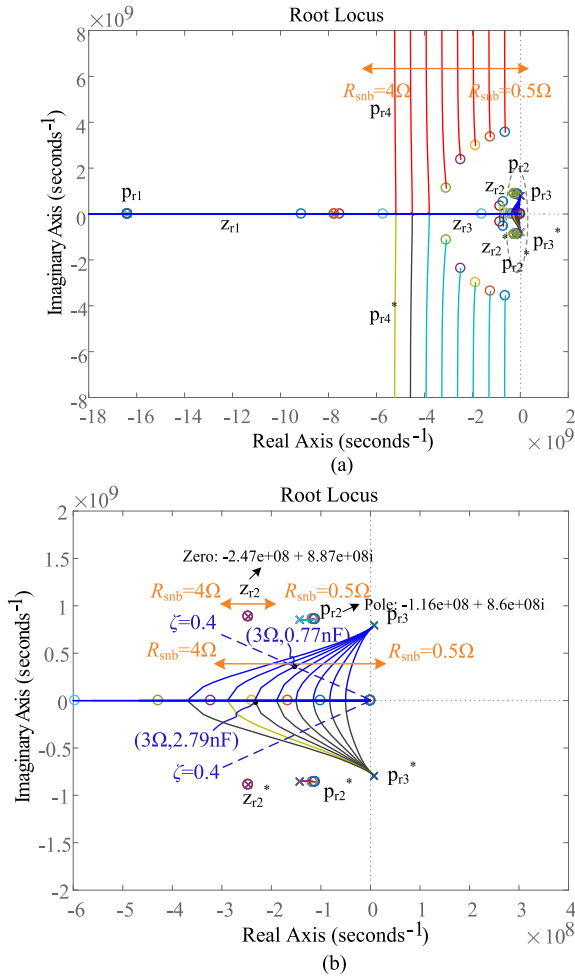


Fig. 8. (a) Root locus diagram of $M(s) = 0$ and $N(s) = 0$ for parameter C_{snb} (R_{snb} from 0.5 to 4 Ω). (b) Enlarged root locus diagram.

ratio of p_{r3} and p_{r3}^* is greater than 0.4, and the oscillation can be well damped. When $C_{snb} > 2.79$ nF, the damping ratio is the largest ($\zeta = 1$), and the sustained oscillation can be fully suppressed.

Fig. 9 shows the root locus diagram of the characteristic equation $M(s) = 0$ and $N(s) = 0$ when the snubber resistance R_{snb} changes from 5 to 10 Ω . It can be seen that no matter how C_{snb} changes, there are always two pairs of complex conjugate solutions p_{r2}, p_{r2}^* and p_{r3}, p_{r3}^* . Fig. 9(b) shows the enlarged root locus diagram of $M(s) = 0$ and $N(s) = 0$. According to Fig. 9(b), z_{r2}, z_{r2}^* and p_{r2}, p_{r2}^* still form dipoles, and their influence on the system performance can still be ignored. However, the dominant poles p_{r3}, p_{r3}^* always have oscillation terms, so the oscillation cannot be fully suppressed. When the snubber resistance $R_{snb} = 5 \Omega$, if $C_{snb} > 0.45$ nF, the damping ratio of p_{r3} and p_{r3}^* is greater than 0.4, and the oscillation can be well damped. When the snubber resistance $R_{snb} = 10 \Omega$, the damping ratio of dominant poles p_{r3} and p_{r3}^* is always less than 0.4 in the process of C_{snb} changing from zero to infinity. Therefore, their suppression effect on the sustained oscillation is not well, and these design values should be excluded.

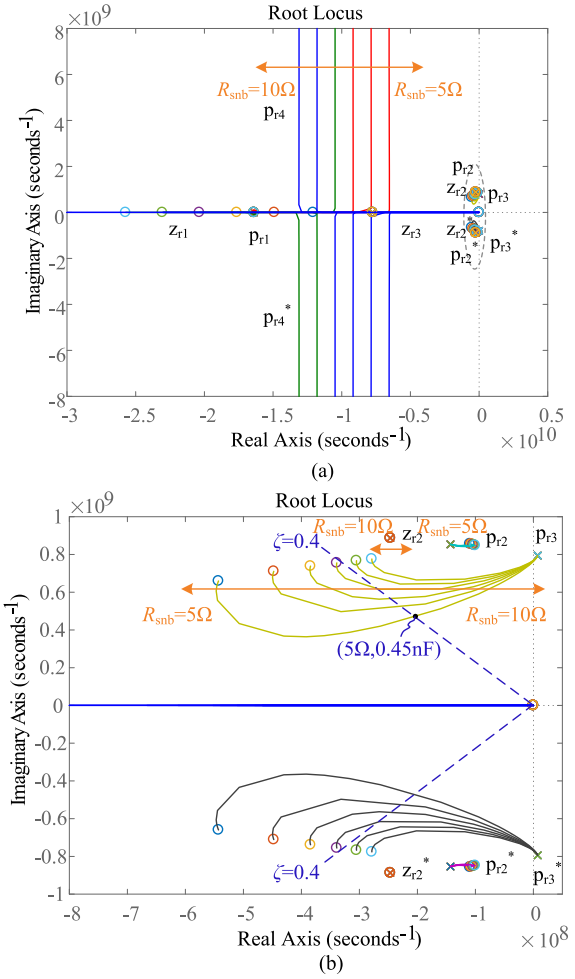


Fig. 9. (a) Root locus diagram of $M(s) = 0$ and $N(s) = 0$ for parameter C_{snb} (R_{snb} from 5 to 10 Ω). (b) Enlarged root locus diagram.

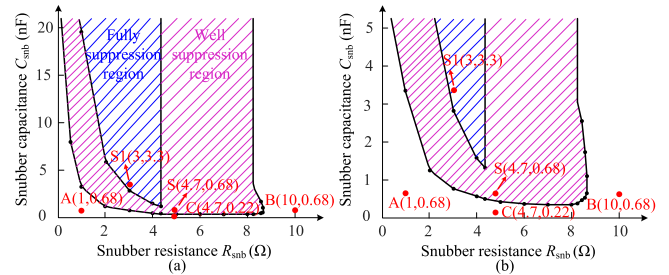


Fig. 10. (a) $R_{snb} - C_{snb}$ region where the sustained oscillation is considered to be fully or well suppressed. (b) Enlarged view when the range of C_{snb} is 0 to 5 nF.

According to the above analysis method, it can be concluded that when the snubber resistance $R_{snb} = 1 \Omega, 3 \Omega$, and 5Ω , the design regions of C_{snb} are $C_{snb} > 3.35$ nF ($\zeta > 0.4$), $C_{snb} > 18.9$ nF ($\zeta = 1$), $C_{snb} > 0.77$ nF ($\zeta > 0.4$), $C_{snb} > 2.79$ nF ($\zeta = 1$), and $C_{snb} > 0.45$ nF ($\zeta > 0.4$), respectively. In addition, when the snubber resistance R_{snb} changes, such as $R_{snb} = 2 \Omega$ and $R_{snb} = 4 \Omega$, the design regions of C_{snb} are $C_{snb} > 1.28$ nF ($\zeta > 0.4$), $C_{snb} > 5.93$ nF ($\zeta = 1$), $C_{snb} > 0.56$ nF ($\zeta > 0.4$), and $C_{snb} > 1.54$ nF ($\zeta = 1$), respectively. Using the same method, the final RC design region is obtained, as shown in Fig. 10(a). The RC

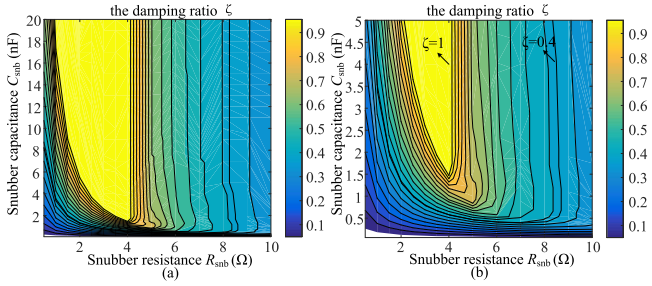


Fig. 11. (a) Relationship among snubber resistance R_{snb} , snubber capacitance C_{snb} , and damping ratio ζ . (b) Enlarged view when the range of C_{snb} is 0 to 5 nF.

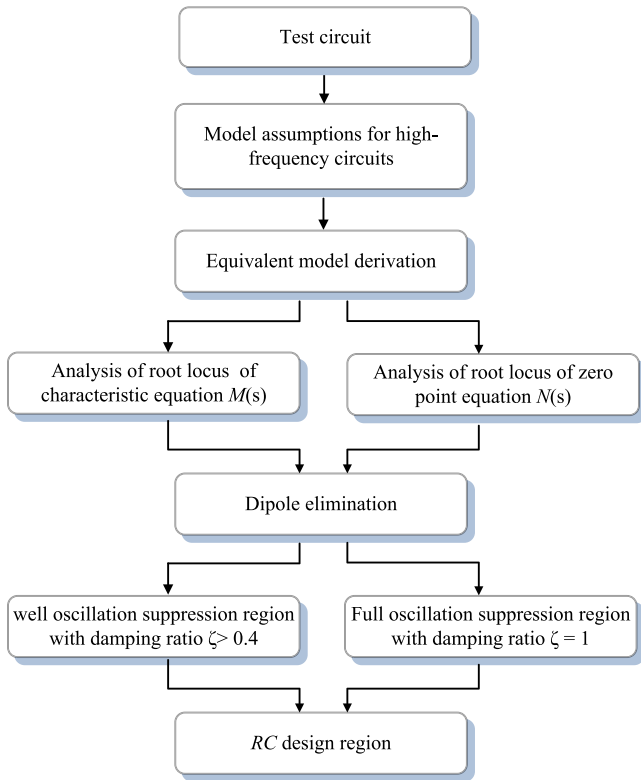


Fig. 12. Method for obtaining RC region.

values in the blue shaded region enable the sustained oscillation to be fully suppressed and the RC values in the purple shaded region enable the oscillation to be well suppressed. Fig. 11 shows the contour plot of snubber resistance, snubber capacitance, and damping ratio of dominant pole p_{r3} . It can be seen when R_{snb} is large, the damping ratio of dominant pole p_{r3} is always less than 0.4 in the process of C_{snb} changing from zero to infinity.

As described above, the method for obtaining the RC region can be summarized, as shown in Fig. 12. It is noticeable that the analysis of the equivalent equation is divided into two parts: drawing the pole root locus and the zero root locus. Once the dipole is formed between the zero and the pole, the effect of the pole on the system performance can be ignored. This method can stimulate an idea for how to analyze and improve the performance of high-order systems.

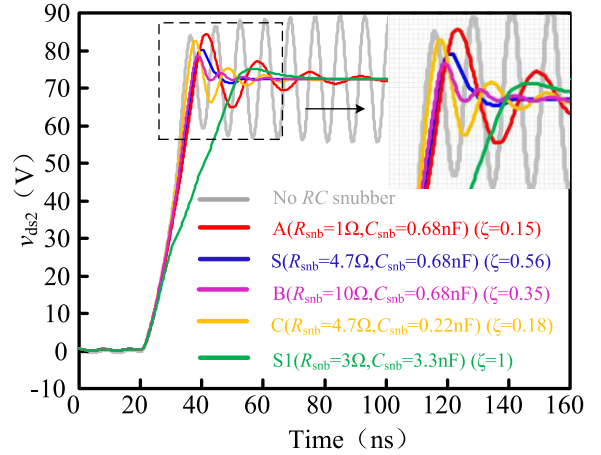


Fig. 13. Simulation comparison of the oscillation suppression effect (within the RC design region, outside the RC design region, and no RC snubber).

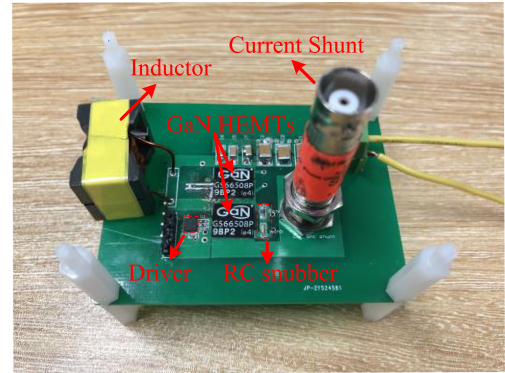


Fig. 14. Experimental configuration and prototype of a double pulse test circuit.

IV. SIMULATION AND EXPERIMENTAL VERIFICATION

A. Simulation Verification

The simulation is performed to verify the above analysis through the Ltpice software. The simulation circuit is a double pulse circuit and all the device parasitic parameters are taken into account. Especially, the switching device is GS66508P using the manufacturer's LTspice model. The input voltage V_{in} is 70 V and the inductor current I_L is 8 A. In order to verify the oscillation suppression effect of the designed RC region, the oscillation suppression effect within the region is compared with that outside the region. In the designed RC region, we select point S (4.7 Ω , 0.68 nF) in the well suppressed region and point S1 (3 Ω , 3.3 nF) in the fully suppressed region to compare their oscillation suppression effect with these points locating outside the designed region. The selected values outside the region are shown in Fig. 10(b), which include points A (1 Ω , 0.68 nF), B (10 Ω , 0.68 nF), and C (4.7 Ω , 0.22 nF).

Fig. 13 shows the simulation result, which is a comparison of the oscillation suppression effect (within the designed RC region, outside the region, and no RC snubber). It can be seen that the sustained oscillation within the designed region (point S and point S1) can be well suppressed. However, for these points outside the RC design region (including points A, B, and C), the

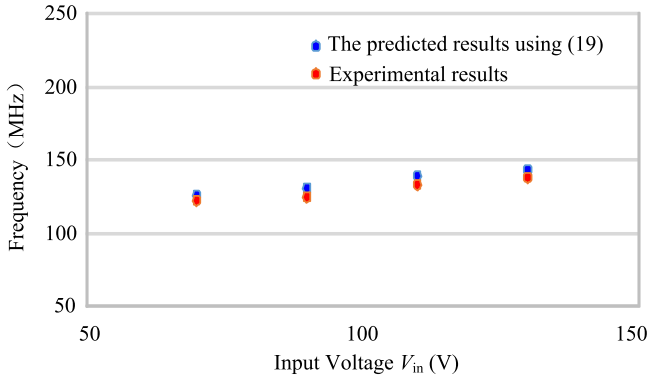


Fig. 15. Comparison of prediction frequency and experimental measurement frequency.

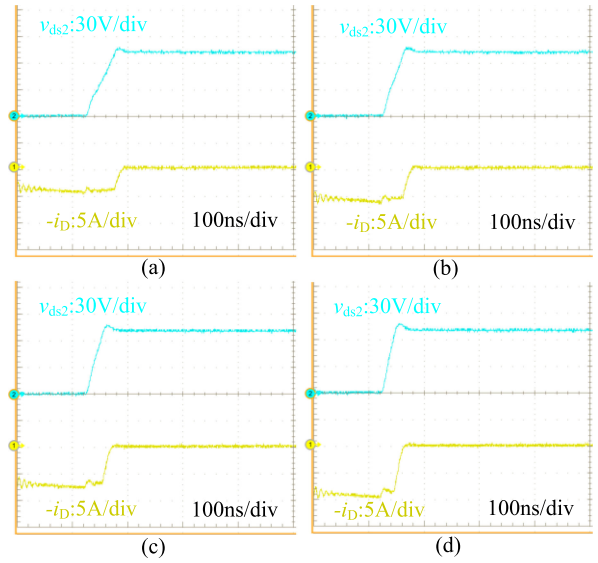


Fig. 18. Oscillation suppression effect for the proposed RC design method (point S1) under different inductor currents. (a) $I_L = 4$ A. (b) $I_L = 6$ A. (c) $I_L = 8$ A. (d) $I_L = 10$ A.

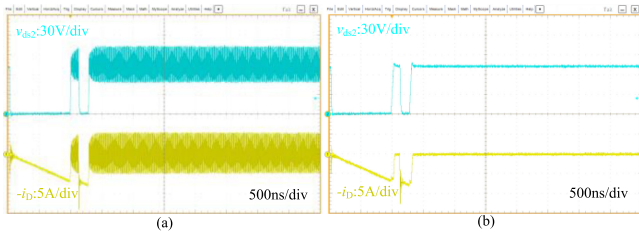


Fig. 16. Experimental results without RC snubber and with the RC snubber. (a) Without RC snubber. (b) With RC snubber.

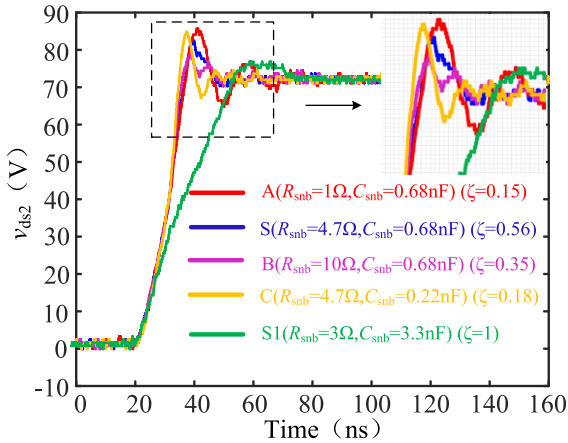


Fig. 17. Experimental results' comparison of the oscillation suppression effect within the RC design region and outside the RC design region.

suppression effects of the sustained oscillation are not as good as those within the RC design region.

B. Experimental Verification

Fig. 14 shows the experimental prototype of the double pulse test circuit. The input voltage of the experiment is 70 V and the inductor current is 8 A, which is consistent with the simulation conditions. Its specifications and circuit parameters are the same as those given in Table II. Specifically, the switching device is GS66508P, and the driver is the LM5114. The current shunt is SSDN-10, which has a high bandwidth (2000 MHz) and the accurate resistance (0.1 Ω).

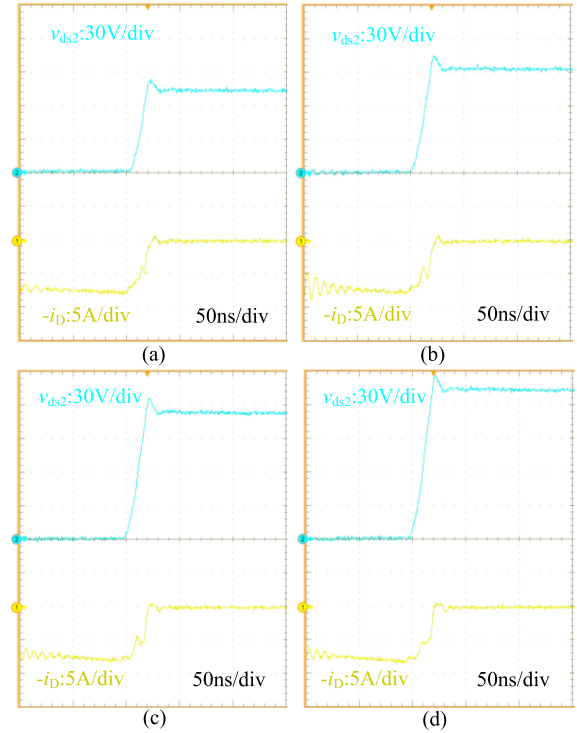


Fig. 19. Oscillation suppression effect for the proposed RC design method (point S) under different input voltages ($I_L = 8$ A). (a) $V_{in} = 70$ V. (b) $V_{in} = 90$ V. (c) $V_{in} = 110$ V. (d) $V_{in} = 130$ V.

In order to verify the accuracy of the proposed model, when no RC is added, the sustained oscillation frequency predicted by (19) is compared with the experimental results, as shown in Fig. 15. It can be seen that when the input voltage changes, the experimentally measured oscillation frequency is in good agreement with the predicted oscillation frequency. Therefore, the proposed model has good accuracy.

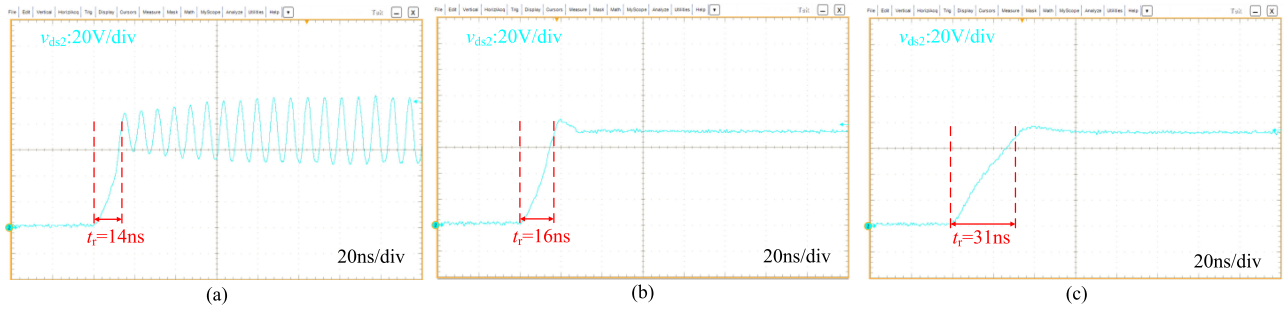


Fig. 20. Switching speed without RC and with RC snubber circuit. (a) Without RC snubber. (b) With RC snubber (point S). (c) With RC snubber (point $S1$).

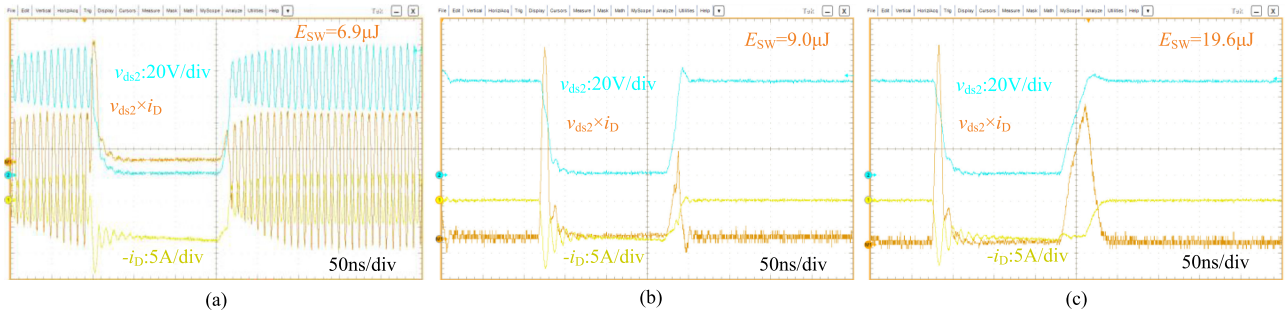


Fig. 21. Energy loss without RC and with RC snubber circuit ($I_L = 8$ A). (a) Without RC snubber. (b) With RC snubber (point S). (c) With RC snubber (point $S1$).

Fig. 16 shows the experimental results without and with the RC snubber. When the RC snubber is adopted, the sustained oscillation of v_{ds2} can be well suppressed. Fig. 17 shows the experimental verification results within the designed RC region and outside the region. It can be observed that the oscillation can be suppressed satisfactorily within the region (point S and point $S1$). However, whether R_{snb} is larger (point B), smaller (point A) or C_{snb} is smaller (point C), the experimental results indicate that they have longer oscillation time. The final experimental results are consistent with the theoretical analysis and simulation results. These results support our conclusion that the well oscillation suppression effect can be obtained by an elaborately designed RC snubber circuit.

Fig. 18 shows the sustained oscillation suppression effect for the proposed RC design method under different inductor currents. The RC parameter is selected in the fully suppressed region (point $S1$). It can be seen that when the inductor current changes from 4 to 10 A, the sustained oscillation of v_{ds2} can still be fully suppressed, which indicates that the proposed RC design method still has satisfied oscillation suppression effect for different load currents.

When the input voltage is different, the point S is still in the RC design region. In order to further verify the effectiveness of our design method, the sustained oscillation suppression effect for the proposed RC design method under different input voltages is shown in Fig. 19. It can be concluded that point S can still suppress the sustained oscillation well and has a little effect on the switching speed, which further validates the theoretical analysis.

C. Discussion of Results

According to Fig. 17, although the point $S1$ enables the oscillation to be fully suppressed, it greatly slows down the switching speed, which increases the switching loss. When there is no RC snubber, the rise time t_r of v_{ds2} is 14 ns, as illustrated in Fig. 20(a). When the RC snubber (point $S1$) is added, the rise time t_r of v_{ds2} is 31 ns, as illustrated in Fig. 20(c). It can be seen that the switching speed is greatly slowed down, but the sustained oscillation can be fully suppressed, which improves the reliability of the system. When the RC value is in the well suppressed region (point S), the suppression effect is not as good as that of point $S1$, but it still has a satisfactory oscillation suppression effect than those outside the designed RC region. The rise time t_r of v_{ds2} is 16 ns, as shown in Fig. 20(b). Obviously, it has little effect on the switching speed but greatly suppresses the sustained oscillation and improves the reliability of the system. Therefore, point S may be a better choice. However, whether the RC values are selected in the well suppressed region or the fully suppressed region should be determined based on the actual circuit requirements.

D. Loss Analysis Comparison

The effect of the RC snubber on energy loss is explored in this section. Fig. 21 shows the test waveforms and the energy losses under the condition that the inductor current is 8 A. The switching energy losses are tested in the 500 ns time range that includes complete turn-ON and turn-OFF processes. When the RC snubber is not included, the switching energy loss is 6.9 μ J, as

TABLE III
COMPARISON OF ENERGY LOSS AT DIFFERENT POINTS

Current (A)	Outside the design region			With snubbers (S)	With snubbers (S1)	No snubbers	Increased loss between S and no snubbers	
	Point A	Point B	Point C				Increased loss (μJ)	Percentage (%)
4	6.3	5.8	5.7	6.1	16.0	4.4	1.7	38.6
6	8.0	7.2	7.3	7.7	18.4	6.7	1.0	14.9
8	9.6	8.6	8.5	9.0	19.6	6.9	2.1	30.4
10	11.6	10.8	10.7	11.3	22.5	10.8	0.5	4.6

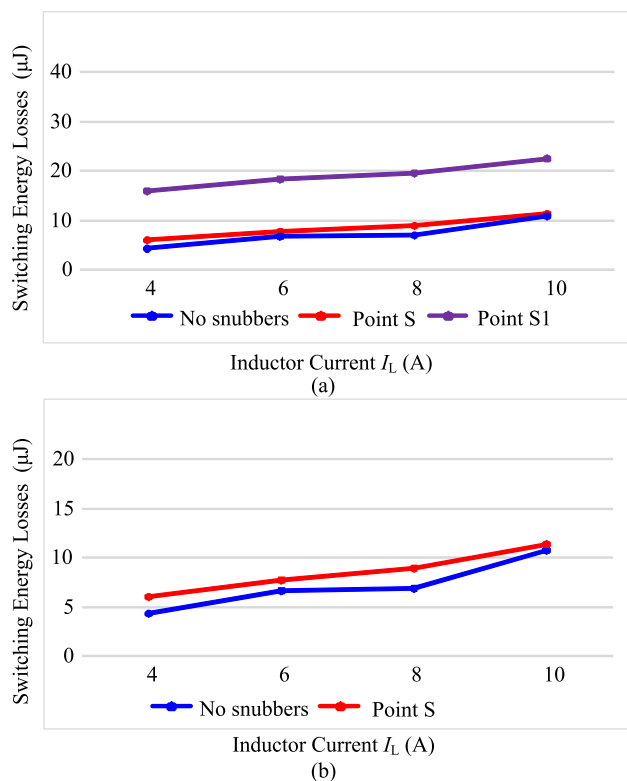


Fig. 22. (a) Comparison of switching energy losses within RC design region (point S and point $S1$) and without RC snubber at different inductor currents. (b) Enlarged view between point S and no snubber.

illustrated in Fig. 21(a). When the RC snubbers locate at point S and point $S1$, the switching energy losses are $9.0 \mu\text{J}$ and $19.6 \mu\text{J}$, respectively, as illustrated in Fig. 21(b) and (c). The switching energy losses at different inductor currents within the RC design region (point S and point $S1$) and without RC snubber are given in Table III, and the corresponding comparison of switching energy losses is shown in Fig. 22. It can be seen from Table III that the points A , B , and C outside the design region have similar switching energy losses with the point S in the design region. However, their oscillation suppression effect is not as good as point S .

It can be concluded that the switching energy losses increase due to the addition of the snubber. In addition, as the inductor current increases, the switching energy losses increase too. According to Fig. 21, the addition of RC snubber has a small effect on the turn-ON speed of the device, which mainly slows down the turn-OFF speed of the device and causes an increase

in the turn-OFF loss. Although point $S1$ can fully suppress the oscillation, it increases the loss more than that of point S . Due to the small cardinality, the relative percentage increase of point S in the loss is large when compared with no RC snubber. However, it is noteworthy that the absolute increment of point S in the loss is very small from Table III and Fig. 22; thus, its effect on the efficiency is negligible. Accordingly, the advantages of the designed RC snubber for improving switching characteristics are much more significant than the disadvantages of the increased total loss. Commonly, the smaller the RC , the faster the switching speed, and the smaller the switching overlap losses in the transient process, which will reduce the impact on the switching speed and switching energy losses. In addition, the larger the damping ratio, the better the oscillation suppression effect. It can be seen from Fig. 10 and Table III that there is no direct relationship between the damping ratio and the switching energy losses because a large RC may also have a small damping ratio but will cause the large switching energy losses. Eventually, reducing the RC values in the design region is beneficial to reduce the switching energy losses while also meeting the well oscillation suppression effect.

V. CONCLUSION

In this article, an RC method with dipole elimination based on the root locus analysis is adopted to suppress the sustained oscillation for GaN transistors, and the RC regions to achieve the well and full suppression effect are quantitatively sketched by using a root locus analysis. It is shown that the oscillation suppression effect within the RC design region is better than that outside the RC design region. In addition, the sustained oscillation can be fully suppressed with a little increase of switching loss or it can be well suppressed with little influence on switching loss when the RC parameters are properly chosen. The simulation and experimental results are consistent with the theoretical analysis, which effectively supports our analytical design. Conclusively, the proposed method indicates a substantial improvement in the switching characteristics and system performance.

The main contributions of this article lie in the following two aspects. On the one hand, it is the first time to adopt the RC snubber to suppress this sustained oscillation, which is very simple and cheap but effective; thus, it has a high practical value. On the second hand, dipole elimination is used for the first time to achieve RC parameter design in the high-order systems; thus, the oscillation can be suppressed well. This method is instructive for high-order circuits to establish dipoles through circuit design

$$\begin{aligned}
& + C_{iss}C_{oss}C_{oss2}LDRG + C_{iss}C_{oss}C_{oss2}LGR_{loop} \\
& + C_{iss}C_{oss}C_{oss2}LsRG + C_{iss}C_{oss}C_{oss2}LsR_{loop} - \\
& C_{gd}C_{oss2}L2LGg_m + C_{iss}C_{oss2}L2LGg_m - C_{gd}C_{oss2}L2LSg_m \\
& + C_{iss}C_{oss2}L2LSg_m - C_{gd}C_{oss2}LDLGg_m + C_{iss}C_{oss2}LDLGg_m \\
& - C_{gd}C_{oss2}LDLSg_m + C_{iss}C_{oss2}LDLSg_m - C_{gd}C_{oss2}LGLSg_m \\
& + C_{iss}C_{oss2}LGLSg_m)s^4 + (C_{oss}C_{oss2}L2 - C_{gd}^2Ls - \\
& C_{gd}^2LG + C_{iss}C_{oss}LG + C_{iss}C_{oss2}LG + C_{oss}C_{oss2}LD \\
& - 2C_{gd}C_{oss2}Ls + C_{iss}C_{oss}Ls + C_{iss}C_{oss2}Ls + \\
& C_{oss}C_{oss2}Ls - C_{gd}^2C_{oss2}RGR_{loop} + C_{iss}C_{oss}C_{oss2}RGR_{loop} \\
& - C_{gd}C_{oss2}L2RGg_m + C_{iss}C_{oss2}L2RGg_m - C_{gd}C_{oss2}LDRGg_m \\
& + C_{iss}C_{oss2}LDRGg_m - C_{gd}C_{oss2}LGR_{loop}g_m + \\
& C_{iss}C_{oss2}LGR_{loop}g_m - C_{gd}C_{oss2}LsRGg_m + C_{iss}C_{oss2}LsRGg_m \\
& - C_{gd}C_{oss2}LsR_{loop}g_m + C_{iss}C_{oss2}LsR_{loop}g_m)s^3 + (C_{iss}C_{oss}RG \\
& - C_{gd}^2RG + C_{iss}C_{oss2}RG + C_{oss}C_{oss2}R_{loop} + C_{oss2}L2g_m - \\
& C_{gd}LGg_m + C_{iss}LGg_m + C_{oss2}LDg_m - C_{gd}LSg_m + C_{iss}LSg_m \\
& - C_{gd}C_{oss2}RGR_{loop}g_m + C_{iss}C_{oss2}RGR_{loop}g_m)s^2 + (C_{oss} + \\
& C_{oss2} - C_{gd}RGG_m + C_{iss}RGG_m + C_{oss2}R_{loop}g_m)s + g_m.
\end{aligned}$$

The coefficients in (21) are shown as follows:

$$\begin{aligned}
Q_1 & = (C_{gd}^2C_{oss2}L2LGR_{snb}V_0 + \\
& C_{gd}^2C_{oss2}L2LsR_{snb}V_0 - C_{iss}C_{oss}C_{oss2}L2LGR_{snb}V_0 - \\
& C_{iss}C_{oss}C_{oss2}L2LsR_{snb}V_0 + C_{gd}^2C_{oss2}I_0L2LGR_{loop}R_{snb} \\
& + C_{gd}^2C_{oss2}I_0L2LsR_{loop}R_{snb} - C_{iss}C_{oss}C_{oss2}I_0L2LGR_{loop}R_{snb} \\
& - C_{iss}C_{oss}C_{oss2}I_0L2LsR_{loop}R_{snb})s^5 + (C_{gd}C_{oss2}I_0L2LsR_{snb} \\
& - C_{gd}^2I_0LDLsR_{snb} - C_{gd}^2I_0LGLsR_{snb} - C_{iss}C_{oss2}I_0L2LGR_{snb} \\
& - C_{gd}^2I_0LDLGR_{snb} - C_{iss}C_{oss2}I_0L2LsR_{snb} + \\
& C_{iss}C_{oss}I_0LDLGR_{snb} + C_{iss}C_{oss}I_0LDLsR_{snb} + \\
& C_{iss}C_{oss}I_0LGLsR_{snb} + C_{gd}^2C_{oss2}L2RGR_{snb}V_0 - \\
& C_{iss}C_{oss}C_{oss2}L2RGR_{snb}V_0 + C_{gd}C_{oss2}L2LGR_{snb}V_0g_m + \\
& C_{gd}^2C_{oss2}I_0L2RGR_{loop}R_{snb} - C_{iss}C_{oss}C_{oss2}I_0L2RGR_{loop}R_{snb} \\
& + C_{gd}C_{oss2}I_0L2LGR_{loop}R_{snb}g_m - \\
& C_{iss}C_{oss2}I_0L2LGR_{loop}R_{snb}g_m + C_{gd}C_{oss2}I_0L2LsR_{loop}R_{snb}g_m \\
& - C_{iss}C_{oss2}I_0L2LsR_{loop}R_{snb}g_m)s^4 + (C_{gd}^2LGR_{snb}V_0 + \\
& C_{gd}^2LsR_{snb}V_0 - C_{gd}^2I_0LDRGR_{snb} - C_{gd}^2I_0LsRGR_{snb} \\
& - C_{oss}C_{oss2}L2R_{snb}V_0 - C_{iss}C_{oss}LGR_{snb}V_0 - \\
& C_{iss}C_{oss}LsR_{snb}V_0 - C_{iss}C_{oss2}I_0L2RGR_{snb} - \\
& C_{oss}C_{oss2}I_0L2R_{loop}R_{snb} + C_{iss}C_{oss}I_0LDRGR_{snb} \\
& + C_{iss}C_{oss}I_0LsRGR_{snb} - C_{gd}I_0LDLGR_{snb}g_m + \\
& C_{iss}I_0LDLGR_{snb}g_m - C_{gd}I_0LDLsR_{snb}g_m + C_{iss}I_0LDLsR_{snb}g_m \\
& - C_{gd}I_0LGLsR_{snb}g_m + C_{iss}I_0LGLsR_{snb}g_m + \\
& C_{gd}C_{oss2}L2RGR_{snb}V_0g_m + C_{gd}C_{oss2}I_0L2RGR_{loop}R_{snb}g_m \\
& - C_{iss}C_{oss2}I_0L2RGR_{loop}R_{snb}g_m)s^3 + (C_{oss}I_0LDR_{snb} \\
& - C_{oss2}I_0L2R_{snb} - C_{gd}I_0LsR_{snb} + C_{oss}I_0LsR_{snb} + \\
& C_{gd}^2RGR_{snb}V_0 - C_{iss}C_{oss}RGR_{snb}V_0 + C_{gd}LGR_{snb}V_0g_m \\
& - C_{oss2}I_0L2R_{loop}R_{snb}g_m - C_{gd}I_0LDRGR_{snb}g_m \\
& + C_{iss}I_0LDRGR_{snb}g_m - C_{gd}I_0LsRGR_{snb}g_m + \\
& C_{iss}I_0LsRGR_{snb}g_m)s^2 + (I_0LDR_{snb}g_m - C_{oss}R_{snb}V_0 + \\
& C_{gd}RGR_{snb}V_0g_m)s \\
P_1 & = (C_{gd}^2C_{oss2}L2LG V_0 + C_{gd}^2C_{oss2}L2Ls V_0 \\
& - C_{iss}C_{oss}C_{oss2}L2LG V_0 - C_{iss}C_{oss}C_{oss2}L2Ls V_0 + \\
& C_{gd}^2C_{oss2}I_0L2LGR_{loop} + C_{gd}^2C_{oss2}I_0L2LsR_{loop} - \\
& C_{iss}C_{oss}C_{oss2}I_0L2LGR_{loop} - C_{iss}C_{oss}C_{oss2}I_0L2LsR_{loop})s^4 \\
& + (C_{gd}^2C_{oss2}L2RG V_0 - C_{gd}^2I_0LDLs - C_{gd}^2I_0LGLs - \\
& C_{gd}^2I_0LDLg - C_{iss}C_{oss2}I_0L2Lg + C_{gd}C_{oss2}I_0L2Ls - \\
& C_{iss}C_{oss2}I_0L2Ls + C_{iss}C_{oss}I_0LDLg + C_{iss}C_{oss}I_0LDLs \\
& + C_{iss}C_{oss}I_0LGLs - C_{iss}C_{oss}C_{oss2}L2RG V_0 + \\
& C_{gd}C_{oss2}L2LGV_0g_m + C_{gd}^2C_{oss2}I_0L2RGR_{loop} - \\
& C_{iss}C_{oss}C_{oss2}I_0L2RGR_{loop} + C_{gd}C_{oss2}I_0L2LGR_{loop}g_m -
\end{aligned}$$

$$\begin{aligned}
& C_{iss}C_{oss2}I_0L2LGR_{loop}g_m + C_{gd}C_{oss2}I_0L2LsR_{loop}g_m - \\
& C_{iss}C_{oss2}I_0L2LsR_{loop}g_m)s^3 + (C_{gd}^2LG V_0 + C_{gd}^2Ls V_0 - \\
& C_{oss}C_{oss2}L2 V_0 - C_{iss}C_{oss}LG V_0 - C_{iss}C_{oss}Ls V_0 - C_{gd}^2I_0LDRG \\
& - C_{gd}^2I_0LsRG - C_{iss}C_{oss2}I_0L2RG - C_{oss}C_{oss2}I_0L2R_{loop} \\
& + C_{iss}C_{oss}I_0LDRG + C_{iss}C_{oss}I_0LsRG - C_{gd}I_0LDLGRg_m \\
& + C_{iss}I_0LDLGRg_m - C_{gd}I_0LDLsRg_m + C_{iss}I_0LDLsRg_m - \\
& C_{gd}I_0LGLsRg_m + C_{iss}I_0LGLsRg_m + C_{gd}C_{oss2}L2RGV_0g_m + \\
& C_{gd}C_{oss2}I_0L2RGR_{loop}g_m - C_{iss}C_{oss2}I_0L2RGR_{loop}g_m)s^2 + \\
& (C_{oss}I_0LD - C_{oss2}I_0L2 - C_{gd}I_0Ls + C_{oss}I_0Ls + C_{gd}^2RGV_0 \\
& - C_{iss}C_{oss}RGV_0 + C_{gd}LGV_0g_m - C_{oss2}I_0L2R_{loop}g_m - \\
& C_{gd}I_0LDRGg_m + C_{iss}I_0LDRGg_m - C_{gd}I_0LsRGRg_m + \\
& C_{iss}I_0LsRGRg_m)s - C_{oss}V_0 + I_0LDg_m + C_{gd}RGV_0g_m.
\end{aligned}$$

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Jian Chen (Student Member, IEEE) was born in Hubei Province, China, in 1993. He received the B.S. degree in electrical engineering from Qinghai University, Xining, China, in 2016. He is currently working toward the Ph.D. degree in electrical engineering with Chongqing University, Chongqing, China.

His current research interests include wide bandgap device characteristics and models, active gate drivers, and power electronic integration.

Mr. Chen serves as a reviewer for some journals and conferences, such as the *IEEE Journal of Emerging and Selected Topics in Power Electronics* and the *IEEE ECCE-Asia*.



Quanming Luo (Member, IEEE) was born in Chongqing, China, in 1976. He received the B.S., M.S., and Ph.D. degrees in electrical engineering from Chongqing University, Chongqing, China, in 1999, 2002, and 2008, respectively.

From 2002 to 2005, he was a Research and Development Engineer with the Emerson Network Power Co., Ltd., Shenzhen, China. Since 2005, he has been with the College of Electrical Engineering, Chongqing University, where he is currently a Professor. He is the author or co-author of more than

80 papers in journal or conference proceedings. His current research interests include LED driving systems, communication power systems, power harmonic suppression, and power conversion systems in electrical vehicles.



Yuqi Wei (Student Member, IEEE) was born in Henan, China, in 1995. He received the B.S. degree from Yanshan University, Hebei, China, in 2016, and the M.S. degrees from the University of Wisconsin-Milwaukee, Milwaukee, WI, USA, in 2018, and Chongqing University, Chongqing, China, in 2019, respectively, all in electrical engineering. He is currently working toward the Ph.D. degree with the University of Arkansas, Fayetteville, AR, USA.

His current research interests include topology, modeling and control of dc/dc power converters and power factor correction ac/dc converters, wide bandgap devices, and active gate driving.

Mr. Wei serves as reviewer for the *IEEE TRANSACTIONS ON INDUSTRIAL ELECTRONICS*, the *IEEE Journal of Emerging and Selected Topics in Power Electronics*, the *IEEE TRANSACTIONS ON INDUSTRY APPLICATIONS*, the *IEEE Access*, and the *IET Power Electronics*.



Xinyue Zhang was born in Sichuan Province, China, in 1996. She received the B.S. degree in electrical engineering from the Harbin Institute of Technology, Weihai, China, in 2018. She is currently working toward the master's degree in electrical engineering with Chongqing University, Chongqing, China.

Her current research interests include the analytical modeling and the loss calculation of wide bandgap devices.



Xiong Du (Member, IEEE) received the B.S., M.S., and Ph.D. degrees from Chongqing University, Chongqing, China, in 2000, 2002, and 2005, respectively, all in electrical engineering.

Since 2002, he has been with Chongqing University, where he is currently a Full Professor with the School of Electrical Engineering. From 2007 to 2008, he was a Visiting Scholar with Rensselaer Polytechnic Institute, Troy, NY, USA. His research interest focuses on power electronics system reliability and stability.

Dr. Du was a recipient of the National Excellent Doctoral Dissertation of P.R. China, in 2008.